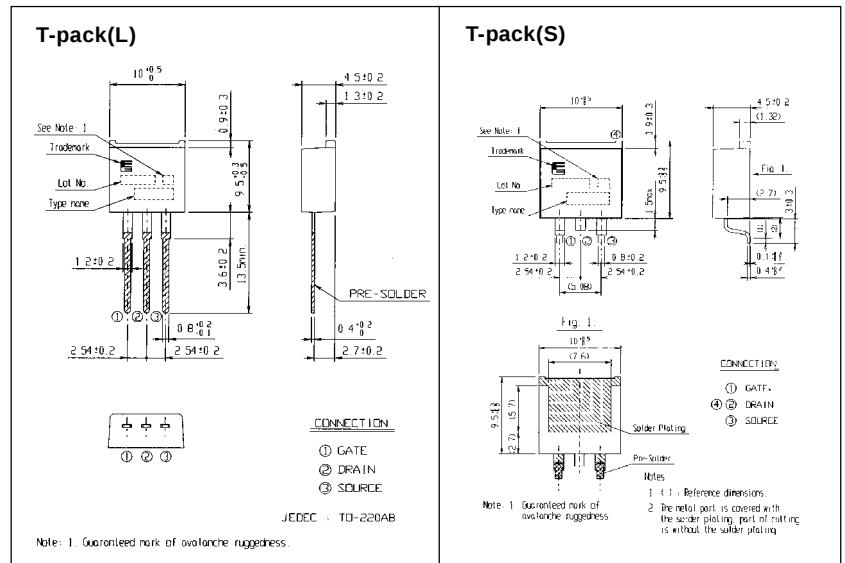


N-CHANNEL SILICON POWER MOSFET**FAP-III B SERIES****■ Features**

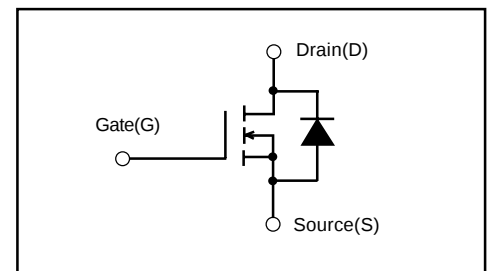
- High speed switching
- Low on-resistance
- No secondary breakdown
- Low driving power
- Avalanche-proof

■ Applications

- Switching regulators
- DC-DC converters
- General purpose power amplifier

■ Outline Drawings**■ Maximum ratings and characteristics****● Absolute maximum ratings (Tc=25°C unless otherwise specified)**

Item	Symbol	Rating	Unit	Remarks
Drain-source voltage	V _{DS}	60	V	
Continuous drain current	I _D	±45	A	
Pulsed drain current	I _D [puls]	±180	A	
Gate-source peak voltage	V _{GS}	±20	V	
Maximum avalanche energy	E _{AV}	461.9	mJ	*1
Maximum power dissipation	P _D	60	W	
Operating and storage temperature range	T _{ch} T _{stg}	+150 -55 to +150	°C	

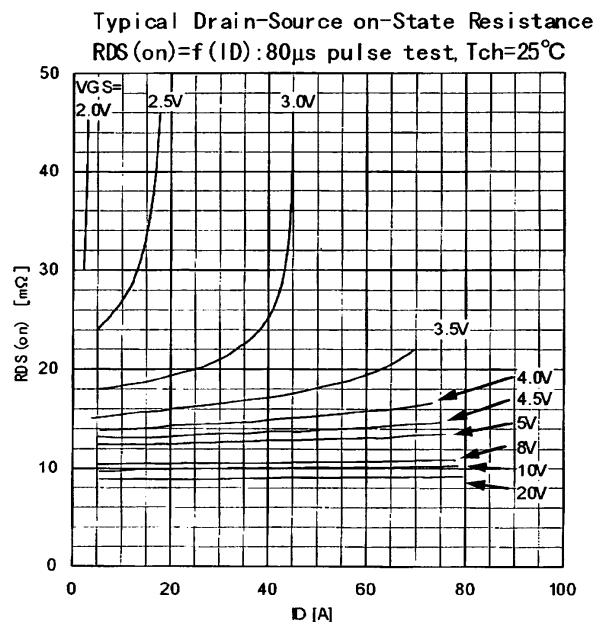
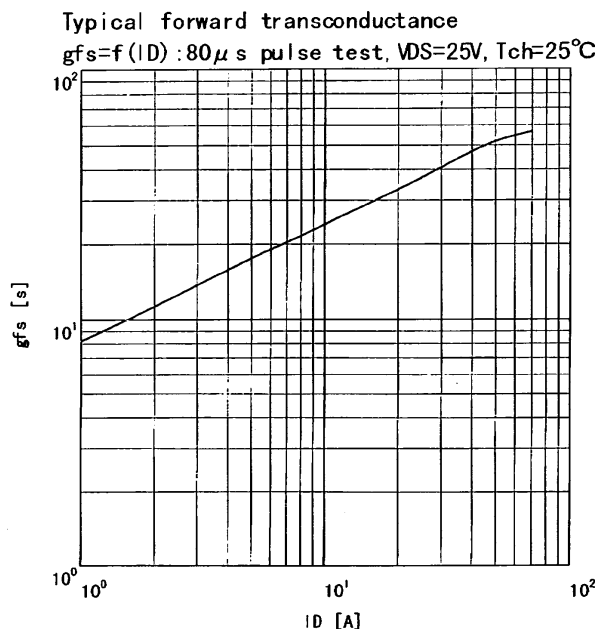
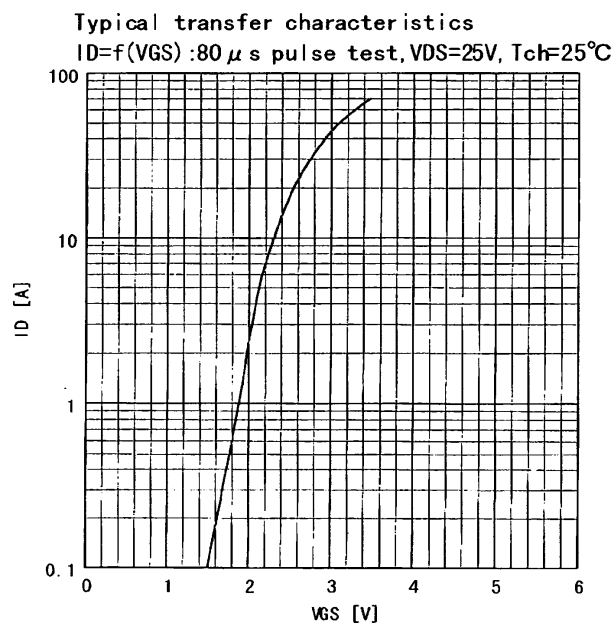
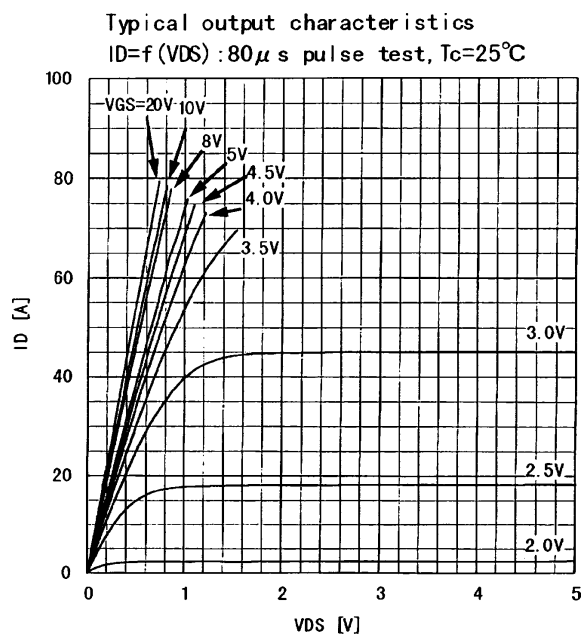
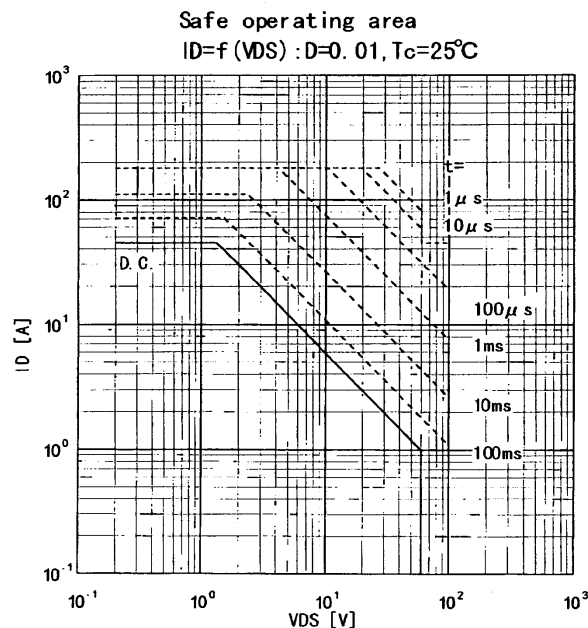
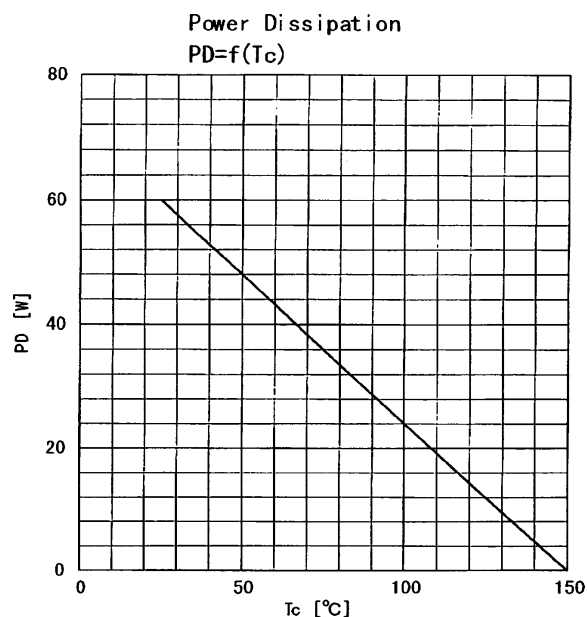
*1 L=0.304mH, V_{CC}=24V**■ Equivalent circuit schematic****● Electrical characteristics (Tc =25°C unless otherwise specified)**

Item	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Drain-source breakdown voltage	V _{(BR)DSS}	I _D =1mA V _{GS} =0V	60			V
Gate threshold voltage	V _{GS(th)}	I _D =1mA V _{DS} =V _{GS}	1.0	1.5	2.0	V
Zero gate voltage drain current	I _{DSS}	V _{DS} =60V V _{GS} =0V		10	500	μA
				0.2	1.0	mA
Gate-source leakage current	I _{GSS}	V _{GS} =±20V V _{DS} =0V		10	100	nA
Drain-source on-state resistance	R _{DS(on)}	I _D =22.5A V _{GS} =10V		15	20	mΩ
				10	12	
Forward transconductance	g _{fs}	I _D =22.5A V _{DS} =25V	15	35		S
Input capacitance	C _{iss}	V _{DS} =25V		2900	4350	pF
Output capacitance	C _{oss}	V _{GS} =0V		930	1400	
Reverse transfer capacitance	C _{rss}	f=1MHz		260	390	
Turn-on time	t _{d(on)}	V _{CC} =30V R _G =10 Ω		13	30	
	t _r	I _D =45A		35	50	
Turn-off time	t _{d(off)}	V _{GS} =10V		190	290	
	t _f			75	140	
Avalanche capability	I _{AV}	L=100μH T _{ch} =25°C	45			A
Diode forward on-voltage	V _{SD}	I _F =45A V _{GS} =0V T _{ch} =25°C		0.95	1.43	V
Reverse recovery time	t _{rr}	I _F =45A V _{GS} =0V		55		ns
Reverse recovery charge	Q _{rr}	-di/dt=100A/μs T _{ch} =25°C		0.10		μC

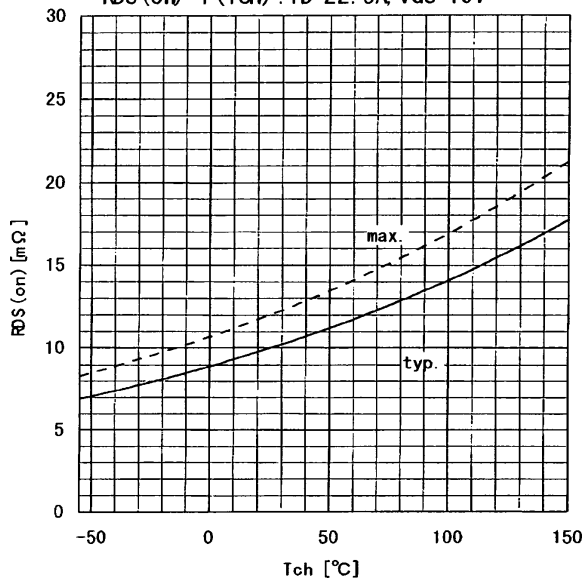
● Thermal characteristics

Item	Symbol	Min.	Typ.	Max.	Units
Thermal resistance	R _{th(ch-c)}			2.08	°C/W
	R _{th(ch-a)}			125.0	°C/W

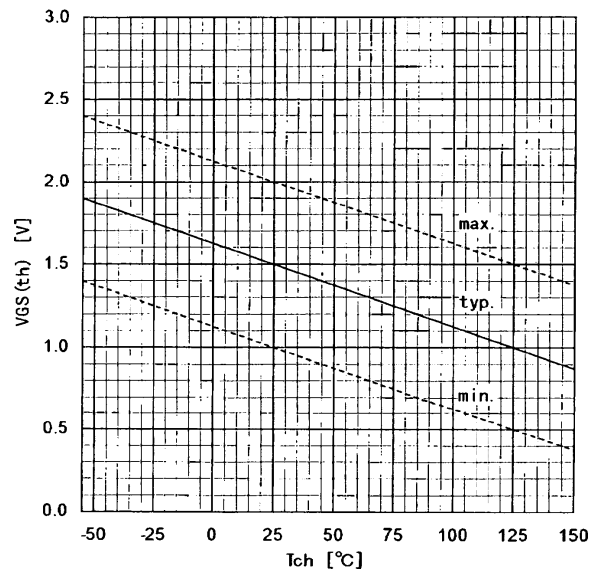
■ Characteristics



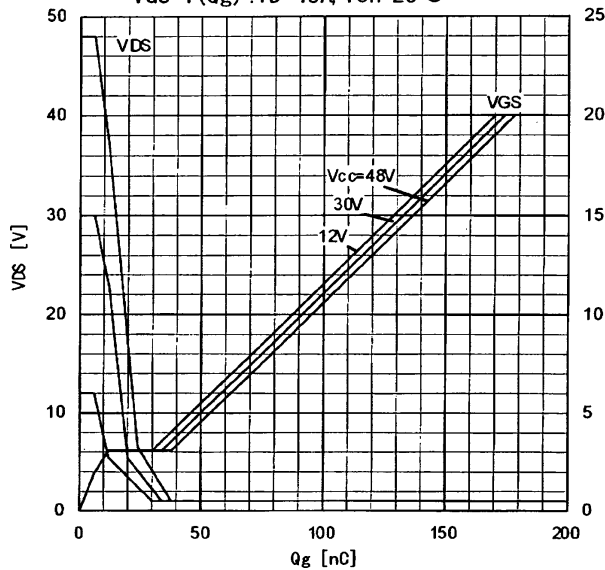
Drain-source on-state resistance
 $R_{DS(on)} = f(T_{ch}) : I_D = 22.5A, V_{GS} = 10V$



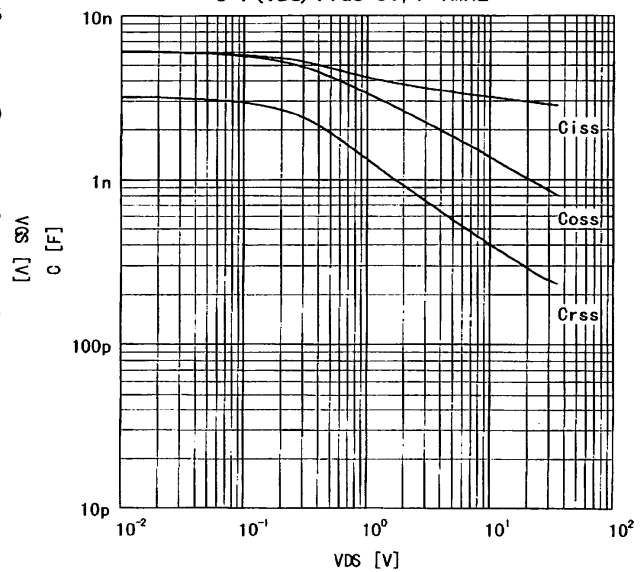
Gate Threshold Voltage vs. T_{ch}
 $V_{GS(th)} = f(T_{ch}) : V_{DS} = V_{GS}, I_D = 1mA$



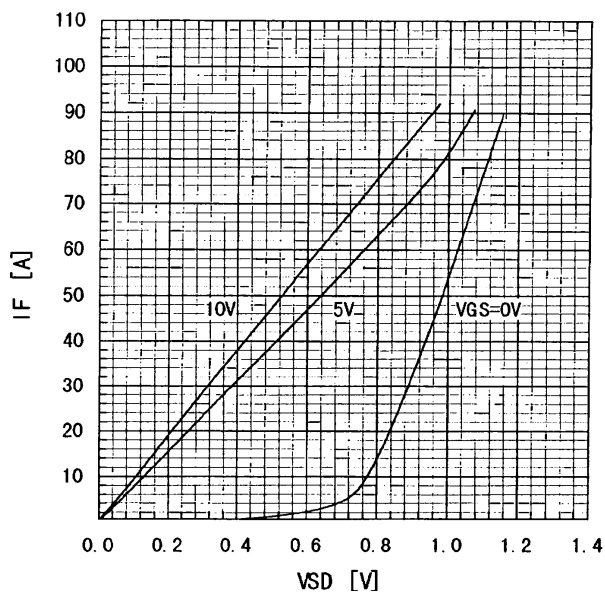
Typical Gate Charge Characteristics
 $V_{GS} = f(Q_g) : I_D = 45A, T_{ch} = 25^{\circ}C$



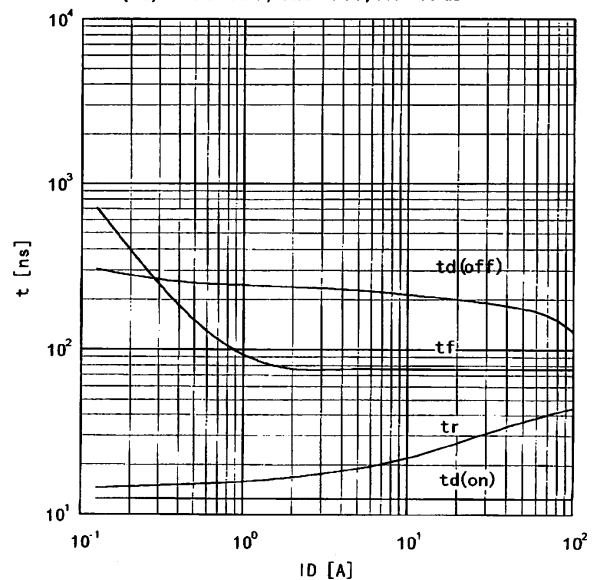
Typical capacitances
 $C = f(V_{DS}) : V_{GS} = 0V, f = 1MHz$



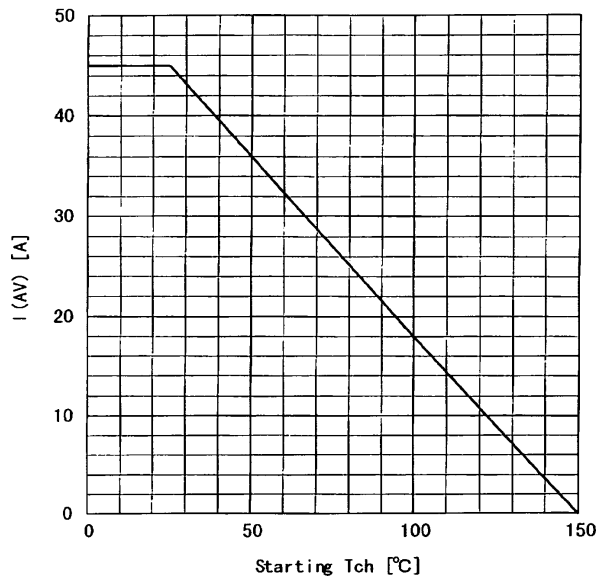
Typical Forward Characteristics of Reverse Diode
 $I_F = f(V_{SD}) : 80\mu s$ pulse test, $T_{ch} = 25^{\circ}C$



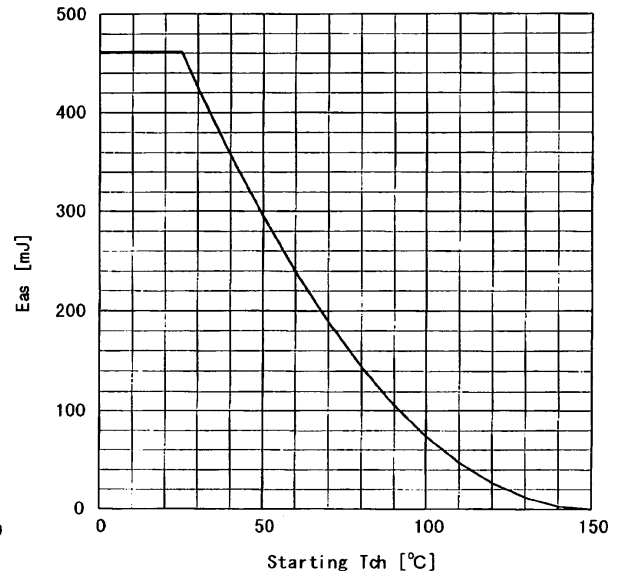
Typical Switching Characteristics vs. I_D
 $t = f(I_D) : V_{CC} = 30V, V_{GS} = 10V, R_G = 10\Omega$



Maximum Avalanche Current vs. starting Tch
 $I_{AV}=f(\text{starting Tch})$



Maximum Avalanche energy vs. starting Tch
 $E_{as}=f(\text{starting Tch}) : V_{CC}=24V, I_{AV} \leq 45A$



Transient thermal impedance
 $Z_{thch}=f(t)$ parameter: $D=t/T$

